

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Excellent CdV/dt effect decline
- ★ Green Device Available
- ★ Advanced high cell density Trench technology

### Product Summary



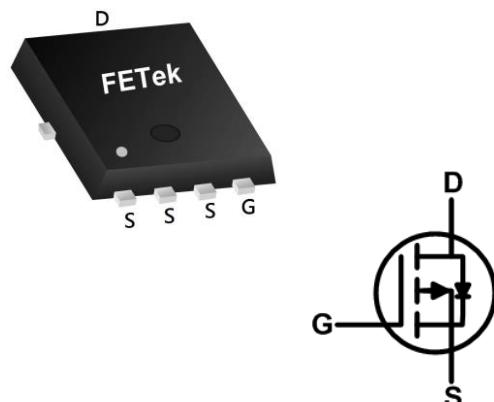
BVDSS	RDS(on)	ID
-40V	13mΩ	-52A

### Description

The FKBA4115 is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The FKBA4115 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### PRPAK5X6 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-52	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-32	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-105	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	146	mJ
I <sub>AS</sub>	Avalanche Current	-54	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	52.1	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	2.4	°C/W

Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-40	---	---	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10\text{V}$ , $I_D=-18\text{A}$	---	10.5	13	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-12\text{A}$	---	15	20	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	$\text{uA}$
		$V_{DS}=-32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55\text{ }^{\circ}\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=-5\text{V}$ , $I_D=-18\text{A}$	---	24	---	S
$Q_g$	Total Gate Charge (-4.5V)	$V_{DS}=-20\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D=-12\text{A}$	---	27.9	---	$\text{nC}$
$Q_{gs}$	Gate-Source Charge		---	7.7	---	
$Q_{gd}$	Gate-Drain Charge		---	7.5	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-15\text{V}$ , $V_{GS}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-1\text{A}$	---	40	---	$\text{ns}$
$T_r$	Rise Time		---	35.2	---	
$T_{d(off)}$	Turn-Off Delay Time		---	100	---	
$T_f$	Fall Time		---	9.6	---	
$C_{iss}$	Input Capacitance	$V_{DS}=-15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	3500	---	$\text{pF}$
$C_{oss}$	Output Capacitance		---	323	---	
$C_{rss}$	Reverse Transfer Capacitance		---	222	---	

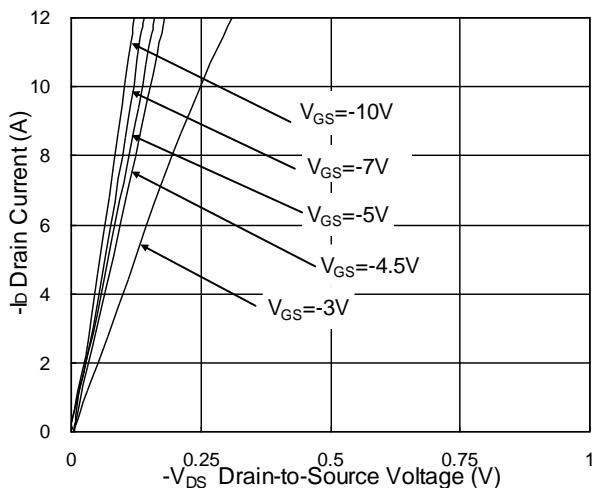
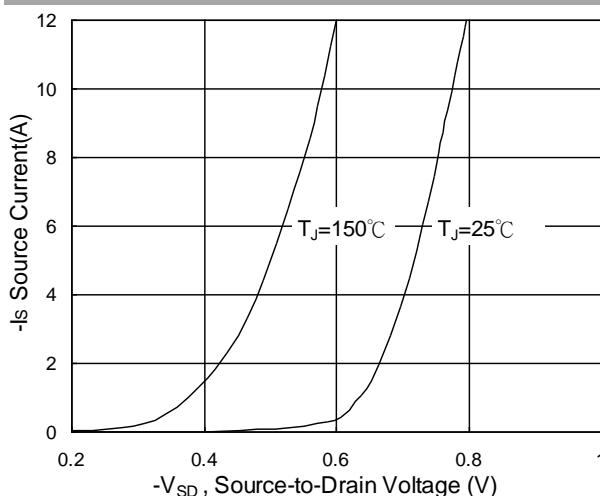
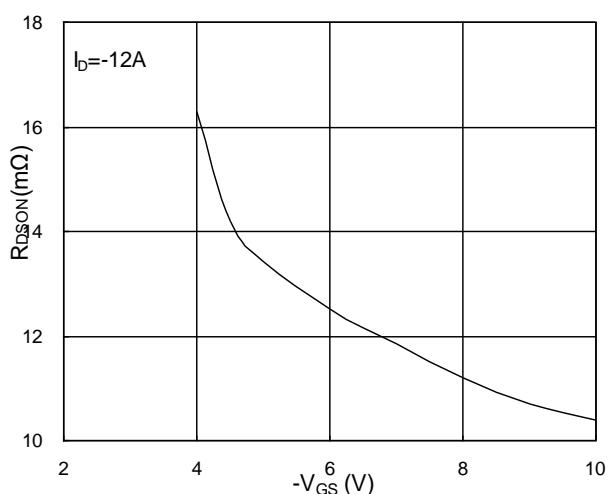
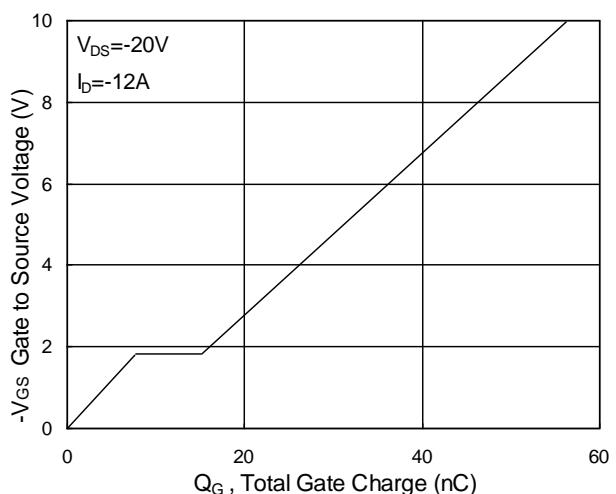
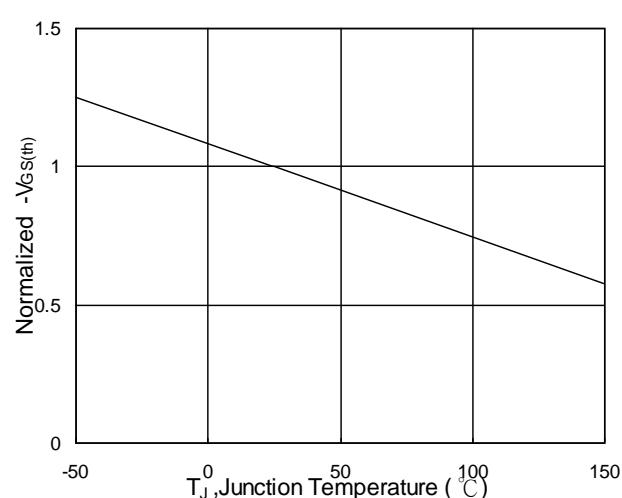
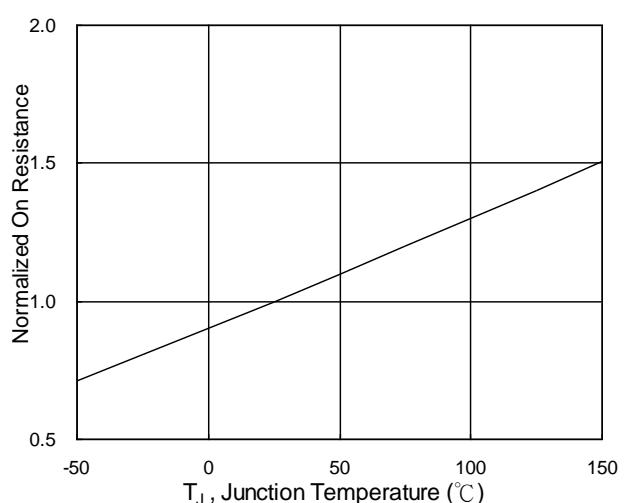
## Diode Characteristics

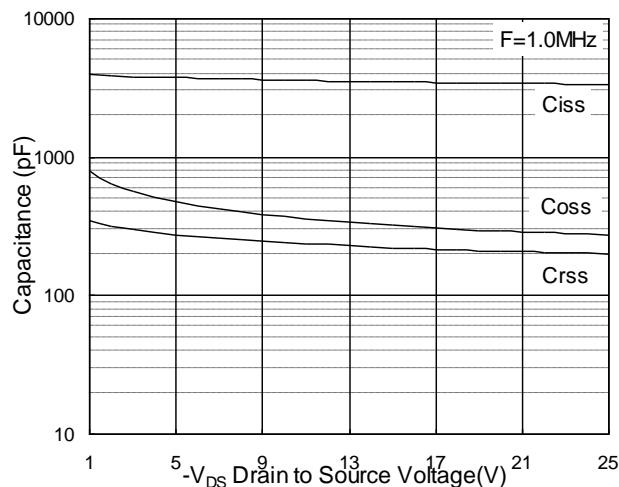
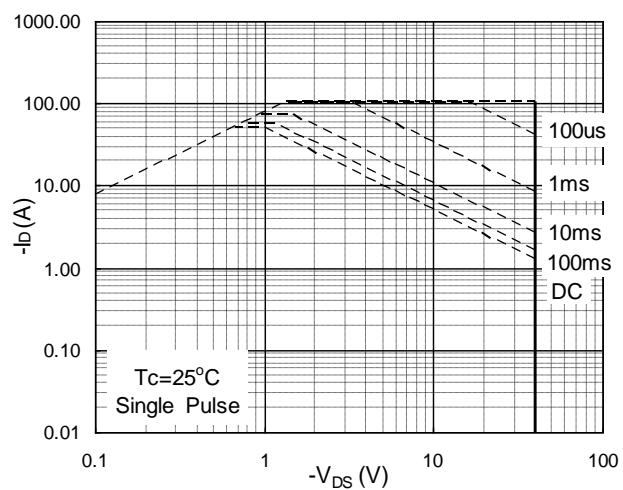
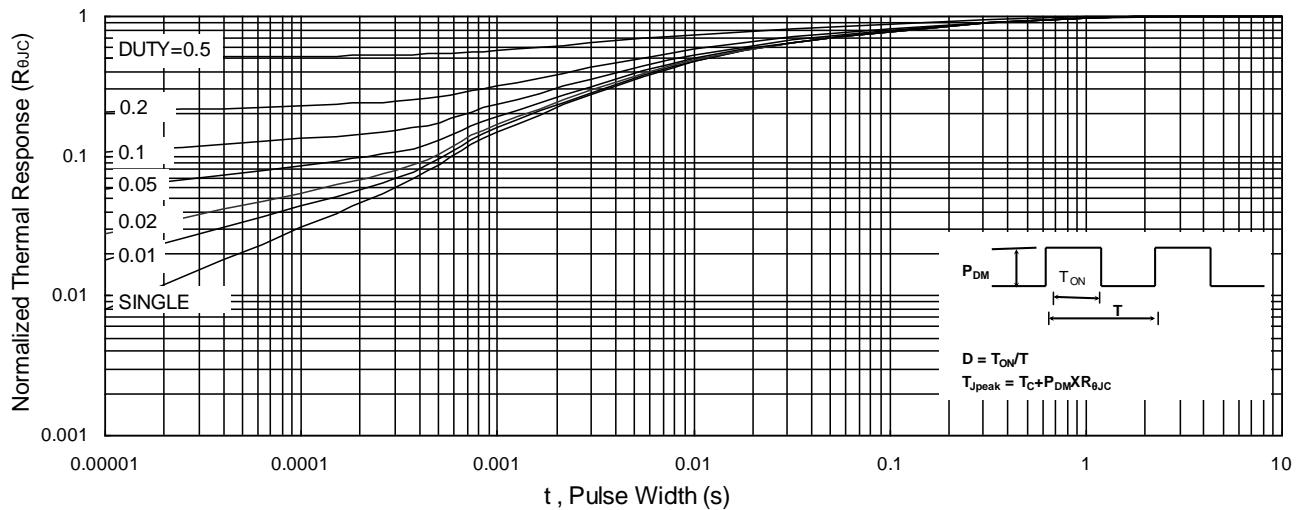
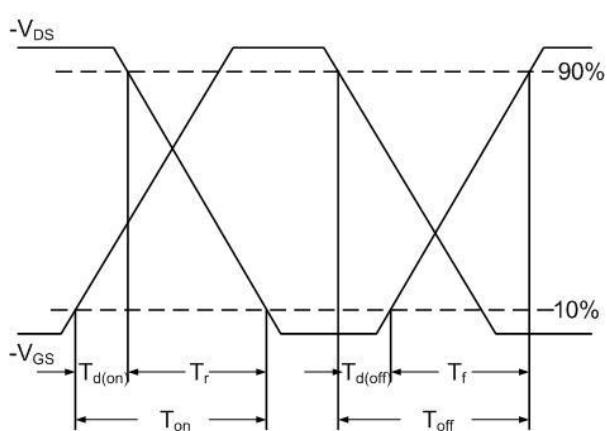
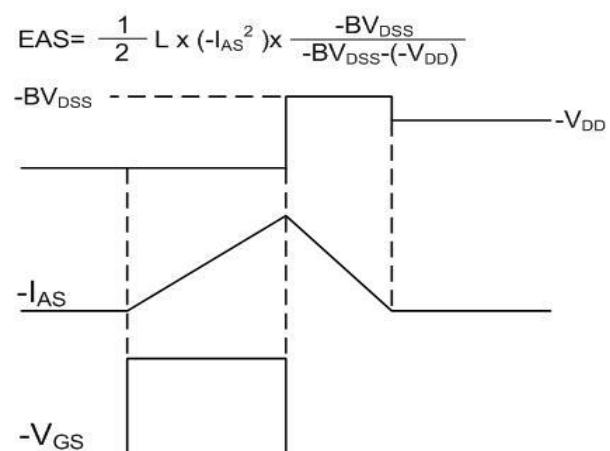
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-30	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=-1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=-25\text{V}$ , $V_{GS}=-10\text{V}$ , $L=0.1\text{mH}$ , $I_{AS}=-54\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

### Typical Characteristics


**Fig.1 Typical Output Characteristics**

**Fig.3 Source Drain Forward Characteristics**

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Waveform**